Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **N. CD1**
2. **D1**
3. **CP1**
4. **N. SD1**
5. **Q1**
6. **N. Q1**
7. **GND**
8. **N. Q2**
9. **Q2**
10. **N. SD2**
11. **CP2**
12. **D2**
13. **N. CD2**
14. **VCC**

**.045”**

**.041”**

 **2 1 14 13 12**

 **5 6 7 8 9**

**11**

**10**

**3**

**4**

**MASK**

**REF**

**Z074U**

J074U

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Vcc**

**Mask Ref: Z074U**

**APPROVED BY: DK DIE SIZE .041” X .045” DATE: 8/8/16**

**MFG: FAIRCHILD THICKNESS .014” P/N: 54ACT74**

**DG 10.1.2**

#### Rev B, 7/19/02